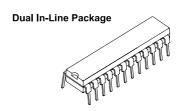


16-bit Constant Current LED Sink Driver

Features

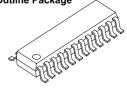
- 16 constant-current output channels
- Constant output current invariant to load voltage change
- Excellent output current accuracy:
 between channels: <±3% (max.), and
 between ICs: <±6% (max.)
- Output current adjusted through an external resistor
- Constant output current range: 5-90 mA
- Fast response of output current, \overline{OE} (min.): 200 ns
- 25MHz clock frequency
- Schmitt trigger input
- 5V supply voltage
- Optional for "Pb-free & Green" Package

Current A	Conditions		
Between Channels Between ICs		Conditions	
< ±3%	< ±6%	I _{OUT} = 10 ~ 60 mA	



CN: P-DIP24-300-2.54 GN: P-DIP24-300-2.54 CNS: SP-DIP24-300-1.78 GNS: SP-DIP24-300-1.78

Small Outline Package



CD: SOP24-300-1.27 GD: SOP24-300-1.27 CF: SOP24-300-1.00 GF: SOP24-300-1.00



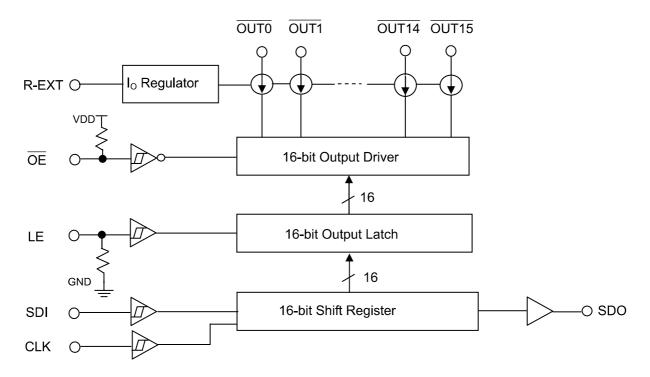
CP\CPA: SSOP24-150-0.64 GP\GPA: SSOP24-150-0.64

Product Description

MBI5026 is designed for LED displays. As an enhancement of its predecessor, MBI5016, MBI5026 exploits PrecisionDrive™ technology to enhance its output characteristics. MBI5026 contains a serial buffer and data latches which convert serial input data into parallel output format. At MBI5026 output stage, sixteen regulated current ports are designed to provide uniform and constant current sinks for driving LEDs within a large range of V_F variations.

MBI5026 provides users with great flexibility and device performance while using MBI5026 in their system design for LED display applications, e.g. LED panels. Users may adjust the output current from 5 mA to 90 mA through an external resistor, R_{ext}, which gives users flexibility in controlling the light intensity of LEDs. MBI5026 guarantees to endure maximum 17V at the output port. The high clock frequency, 25 MHz, also satisfies the system requirements of high volume data transmission.

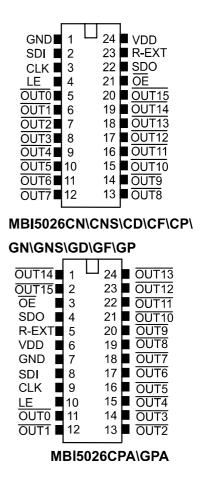
Block Diagram



Terminal Description

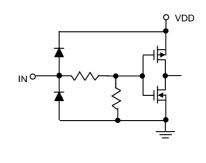
Pin Name	Function
GND	Ground terminal for control logic and current sink
SDI	Serial-data input to the shift register
CLK	Clock input terminal for data shift on rising edge
	Data strobe input terminal
LE	Serial data is transferred to the output latch when LE is high. The data is latched when LE goes low.
OUT0~OUT15	Constant current output terminals
	Output enable terminal
ŌĒ	When OE (active) low, the output drivers are enabled; when OE high, all output drivers are turned OFF (blanked).
SDO	Serial-data output to the following SDI of next driver IC
R-EXT	Input terminal used to connect an external resistor for setting up output current for all output channels
VDD	5V supply voltage terminal

Pin Configuration

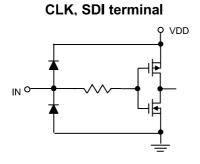


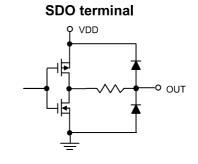
Equivalent Circuits of Inputs and Outputs

OE terminal

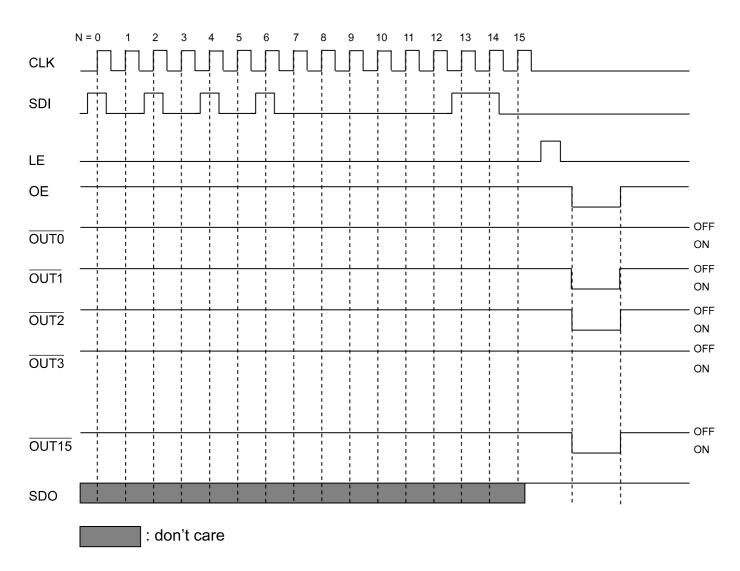


LE terminal





Timing Diagram



Truth Table

CLK	LE	ŌĒ	SDI	OUT0 OUT7 OUT15	SDO
	Н	L	D _n	Dn Dn - 7 Dn - 15	D _{n-15}
	L	L	D _{n+1}	No Change	D _{n-14}
	Н	L	D _{n+2}	$\overline{D_{n+2}} \dots \overline{D_{n-5}} \dots \overline{D_{n-13}}$	D _{n-13}
—	X	L	D _{n+3}	Dn+2Dn-5Dn-13	D _{n-13}
\Box	Х	Н	D _{n+3}	Off	D _{n-13}

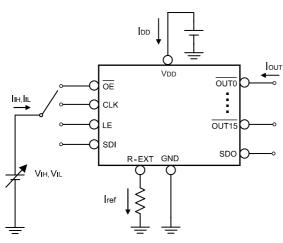
Maximum Ratings

Characteristic			Symbol	Rating		Unit
Supply Voltage		V_{DD}	0~7.0		V	
Input Voltage			V _{IN}	-0.4~V _{DD} + 0.4		V
Output Current			I _{OUT}	+	90	mA
Output Voltage			V_{DS}	-0.5~	+17.0	V
Clock Frequency			F _{CLK}	2	25	MHz
GND Terminal Current			I _{GND}	14	140	mA
	CN	GN		1.80	2.00	
Power Dissipation (On PCB, Ta=25°C)	CNS	GNS	P _D	1.50	1.61	
	CD	GD		2.01	2.19	W
	CF	GF		1.69	1.91] vv
	СР	GP		1.38	1.46	
	CPA	GPA		1.38	1.46	
	CN	GN		55.52	49.9	
	CNS	GNS		66.74	62.28	
Thermal Resistance	CD	GD	P	49.81	45.69	°C/W
(On PCB, Ta=25°C)	CF	GF	$R_{th(j-a)}$	59.01	52.38	J
	СР	GP		72.43	68.48	
	CPA	GPA		72.43	68.48	
Operating Temperature		T _{opr}	-40~+85		°C	
Storage Temperature			T _{stg}	-55~	+150	°C

Electrical Characteristics

Charac	teristic	Symbol	Cond	dition	Min.	Тур.	Max.	Unit
Supply Voltag	е	V_{DD}	-		4.5	5.0	5.5	V
Output Voltag	е	V_{DS}	OUT0 ~ OUT15		-	-	17.0	٧
		I _{OUT}	DC Test Circuit		5	-	90	mA
Output Curren	t	I _{OH}	SDO	SDO		-	-1.0	mA
		l _{OL}	SDO		-	-	1.0	mA
Input Voltage	"H" level	V _{IH}	Ta = -40~85°C		0.8*V _{DD}	-	V_{DD}	V
input voitage	"L" level	V_{IL}	Ta = -40~85°C		GND	-	0.3*V _{DD}	V
Output Leakag	je Current	I _{OH}	V _{OH} =17.0V		-	-	0.5	μΑ
Output Voltage	e SDO	V_{OL}	I _{OL} =+1.0mA		-	-	0.4	V
Output Voltage	300	V _{OH}	I _{OH} =-1.0mA		4.6	-	-	V
Output Curren	t 1	I _{OUT1}	V _{DS} =0.6V R _{ext} =720 Ω		-	26.25	-	mA
Current Skew		dl _{OUT1}	I_{OL} =26.25mA V_{DS} =0.6V R_{ext} =720 Ω		-	±1	±3	%
Output Curren	t 2	I _{OUT2}	V _{DS} =0.8V R _{ext} =360 Ω		-	52.5	-	mA
Current Skew		dl _{OUT2}	I_{OL} =52.5mA V_{DS} =0.8V R_{ext} =360 Ω		-	±1	±3	%
Output Curren Output Voltage		%/dV _{DS}	V _{DS} within 1.0V a	and 3.0V	-	±0.1	-	% / V
Output Curren Supply Voltage		%/dV _{DD}	V _{DD} within 4.5V a	and 5.5V	-	±1	-	% / V
Pull-up Resisto	or	R _{IN} (up)	ŌĒ		250	500	800	ΚΩ
Pull-down Res	istor	R _{IN} (down)	LE		250	500	800	ΚΩ
		I _{DD} (off) 1	R _{ext} =Open, OUT0 ~ OUT15 =Off		-	6	6.8	
	"OFF"	"OFF" I _{DD} (off) 2	R_{ext} =720 Ω , $\overline{\text{OUT0}} \sim \overline{\text{OUT15}}$ =Off		-	8.8	9.6	9.6
Supply Current		I _{DD} (off) 3	R_{ext} =360 Ω , $\overline{\text{OUT0}} \sim \overline{\text{OUT15}}$ =Off		-	12.4	13.2	mA
	"ON"	I _{DD} (on) 1	R _{ext} =720 Ω, $\overline{\text{OU}}$	T0 ~ OUT15 =On	-	8.8	10.8	
		I _{DD} (on) 2	R_{ext} =360 Ω , $\overline{OU^{-}}$	 το ~ OUT15 =On	-	12.3	15.3	

Test Circuit for Electrical Characteristics

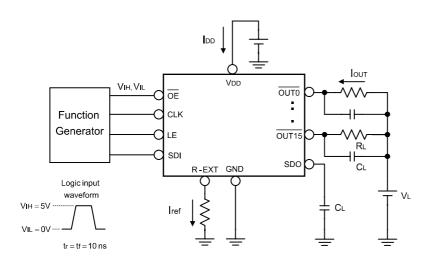


Switching Characteristics

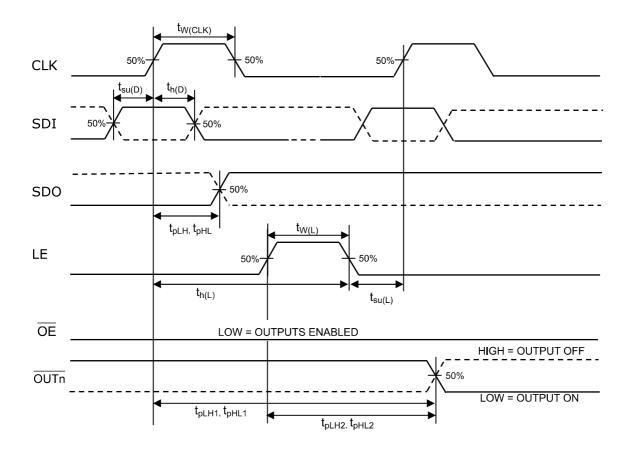
Characteris	stic	Symbol	Condition	Min.	Тур.	Max.	Unit
	CLK - OUTn	t _{pLH1}		-	100	150	ns
Propagation Delay Time	LE - OUTn	t _{pLH2}		-	100	150	ns
("L" to "H")	OE - OUTn	t _{pLH3}		-	50	150	ns
	CLK - SDO	t _{pLH}		15	20	-	ns
	CLK - OUTn	t _{pHL1}	V_{DD} =5.0 V V_{DS} =0.8 V	-	50	100	ns
Propagation Delay Time	LE - OUTn	t _{pHL2}	V _{IH} =V _{DD}	-	50	100	ns
("H" to "L")	OE - OUTn	t _{pHL3}	V_{IL} =GND R _{ext} =300 Ω	-	20	100	ns
	CLK - SDO	t _{pHL}	V_L =4.0 V R _I =52 Ω	15	20	-	ns
	CLK	t _{w(CLK)}	$C_L=10 \text{ pF}$	20	-	-	ns
Pulse Width	LE	t _{w(L)}		20	-	-	ns
	ŌĒ	$t_{w(OE)}$		200	-	-	ns
Hold Time for LE		t _{h(L)}		5	-	-	ns
Setup Time for LE		t _{su(L)}		5	-	-	ns
Hold Time for SDI		t _{h(D)}		10	-	-	ns
Setup Time for SDI		t _{su(D)}		5	-	-	ns
Clock Frequency		F _{CLK}	Cascade Operation	-	-	25.0	MHz
Maximum CLK Rise Time		t _r **		-	-	500	ns
Maximum CLK Fall Time		t _f **		-	-	500	ns
Output Rise Time of Vout (turn off)		t _{or}		-	70	200	ns
Output Fall Time of Vout (t	urn on)	t _{of}		-	40	120	ns

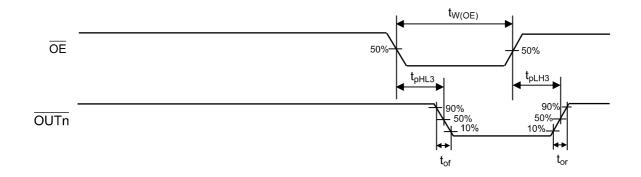
^{**}If the devices are connected in cascade and t_r or t_f is large, it may be critical to achieve the timing required for data transfer between two cascaded devices.

Test Circuit for Switching Characteristics



Timing Waveform



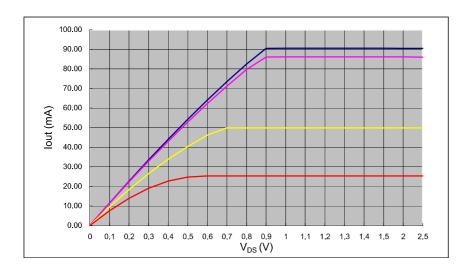


Application Information

Constant Current

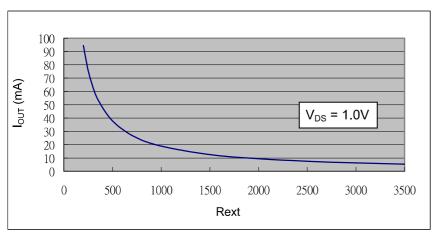
In LED display application, MBI5026 provides nearly no variations in current from channel to channel and from IC to IC. This can be achieved by:

- 1) The maximum current variation between channels is less than ±3%, and that between ICs is less than ±6%.
- 2) In addition, the current characteristic of output stage is flat and users can refer to the figure as shown below. The output current can be kept constant regardless of the variations of LED forward voltages (V_F). This performs as a perfection of load regulation.



Adjusting Output Current

The output current of each channel (I_{OUT}) is set by an external resistor, R_{ext} . The relationship between I_{out} and R_{ext} is shown in the following figure.



Resistance of the external resistor, R_{ext} , in Ω

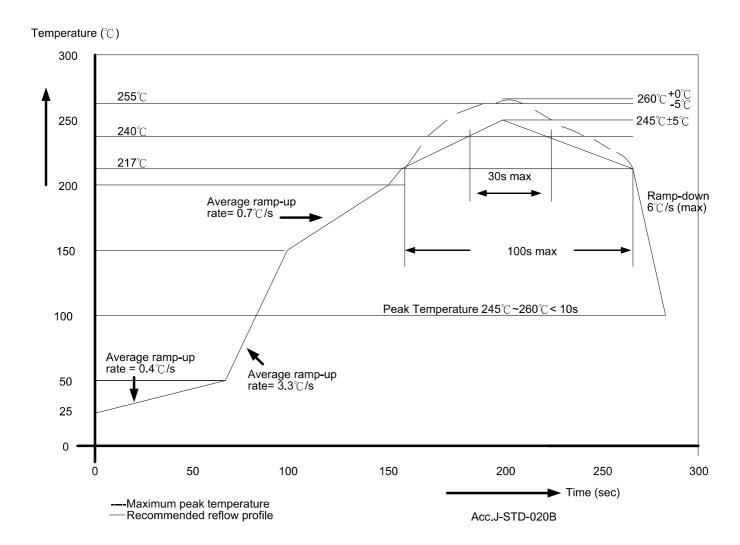
Also, the output current can be calculated from the equation:

$$V_{R-EXT} = 1.26V ; I_{OUT} = (V_{R-EXT} / R_{ext}) x 15$$

where R_{ext} is the resistance of the external resistor connected to R-EXT terminal and V_{R-EXT} is the voltage of R-EXT terminal. The magnitude of current (as a function of R_{ext}) is around 52.5mA at 360 Ω and 26.25mA at 720 Ω .

Soldering Process of "Pb-free & Green" Package Plating*

Macroblock has defines "Pb-Free & Green" to mean semiconductor products that are compatible with the current RoHS requirements and selected **100% pure tin** (Sn) to provide forward and backward compatibility with both the current industry-standard SnPb-based soldering processes and higher-temperature Pb-free processes. Pure tin is widely accepted by customers and suppliers of electronic devices in Europe, Asia and the US as the lead-free surface finish of choice to replace tin-lead. Also, it is backward compatible to standard 215°C to 240°C reflow processes which adopt tin/lead (SnPb) solder paste. However, in the whole Pb-free soldering processes and materials, 100% pure tin (Sn), will all require up to 260°C for proper soldering on boards, referring to J-STD-020B as shown below.

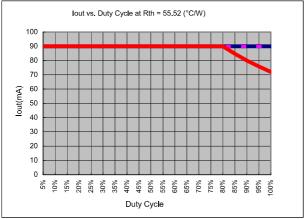


*Note1: For details, please refer to Macroblock's "Policy on Pb-free & Green Package".

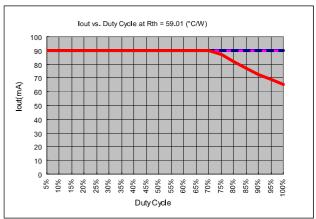
Package Power Dissipation (P_D)

The maximum allowable package power dissipation is determined as $P_D(max) = (Tj - Ta) / R_{th(j-a)}$. When 16 output channels are turned on simultaneously, the actual package power dissipation is $P_D(act) = (I_{DD} \times V_{DD}) + (I_{OUT} \times Duty \times V_{DS} \times 16)$. Therefore, to keep $P_D(act) \le P_D(max)$, the allowable maximum output current as a function of duty cycle is:

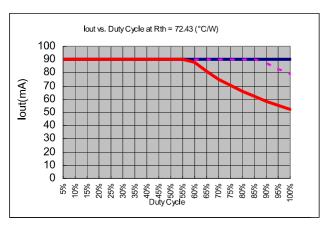
 $I_{OUT} = \{ \; [\; (Tj-Ta) \; / \; R_{th(j-a)} \;] - (I_{DD} \; x \; V_{DD}) \; \} \; / \; V_{DS} / \; Duty \; / \; 16,$ where $Tj=150\,^{\circ}C.$



CN\GN type package



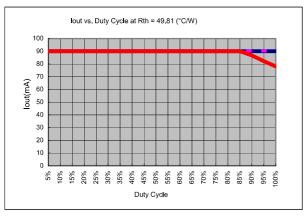
CF\GF type package



CNS\GNS type package



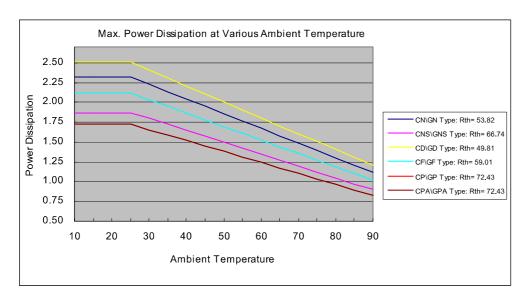
CP\CPA\GP\GPA type package



CD\GD type package

Condition : I _{out} = 90mA · V _{DS} = 1.0V · 16 output channels							
	active						
Device T	уре	R _{th(i-a)} (°	C/W)	Note			
CN	GN	55.52	49.90				
CNS	GNS	66.74	62.28	Ta = 25°℃			
CD	GD	49.81	45.69	Ta = 55°C			
CF	GF	59.01	52.38	——— Ta = 85°C			
CP\CPA	GP\GPA	72.43	68.48				

The maximum power dissipation, $P_D(max) = (Tj - Ta) / R_{th(j-a)}$, decreases as the ambient temperature increases.

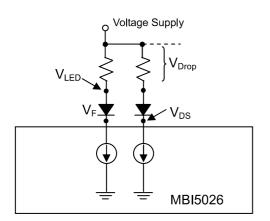


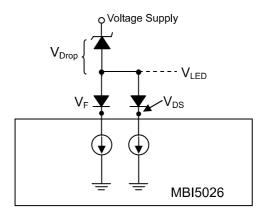
Load Supply Voltage (V_{LED})

MBI5026 are designed to operate with V_{DS} ranging from 0.4V to 1.0V considering the package power dissipating limits. V_{DS} may be higher enough to make $P_{D(act)} > P_{D(max)}$ when $V_{LED} = 5V$ and $V_{DS} = V_{LED} - V_F$, in which V_{LED} is the load supply voltage. In this case, it is recommended to use the lowest possible supply voltage or to set an external voltage reducer, V_{DROP} .

A voltage reducer lets $V_{DS} = (V_{LED} - V_F) - V_{DROP}$.

Resistors or Zener diode can be used in the applications as shown in the following figures.

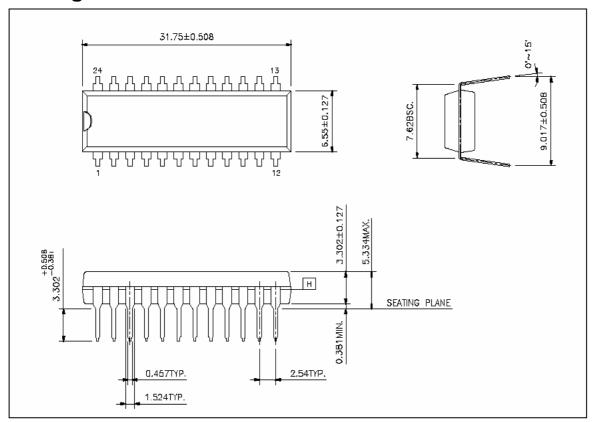




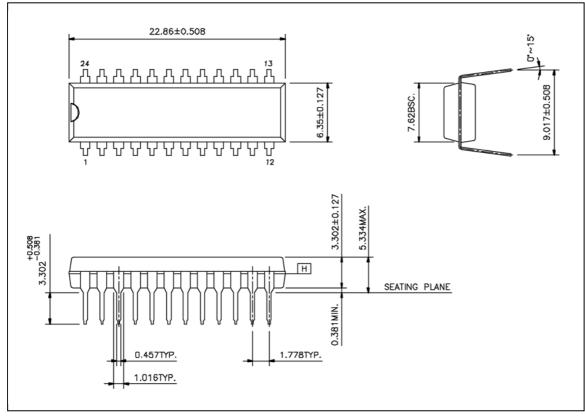
Switching Noise Reduction

LED driver ICs are frequently used in switch-mode applications which always behave with switching noise due to the parasitic inductance on PCB. To eliminate switching noise, refer to "Application Note for 8-bit and 16-bit LED Drivers- Overshoot".

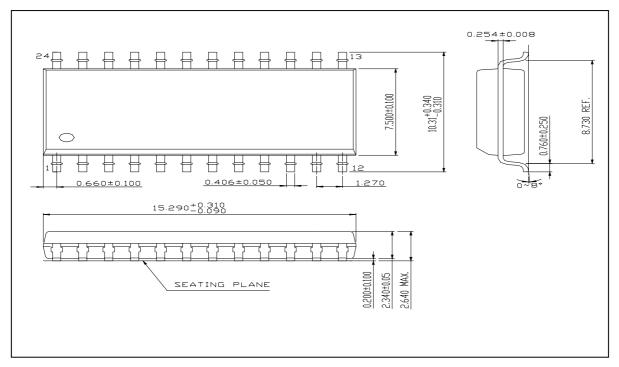
Package Outline



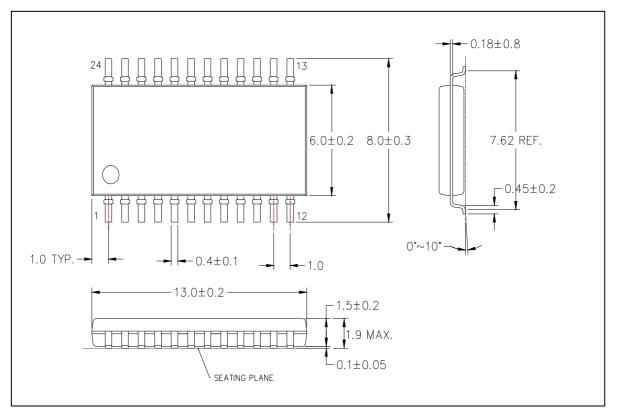
MBI5026CN\GN Outline Drawing



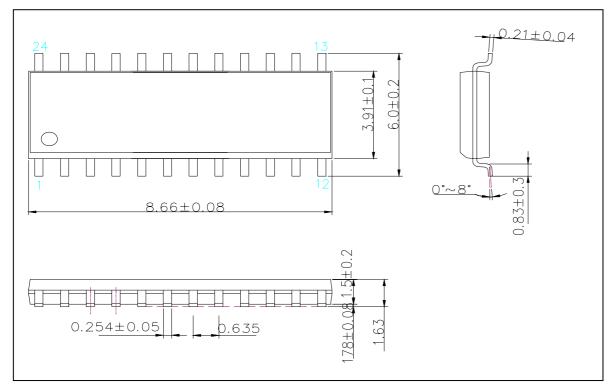
MBI5026CNS\GNS Outline Drawing



MBI5026CD\GD Outline Drawing



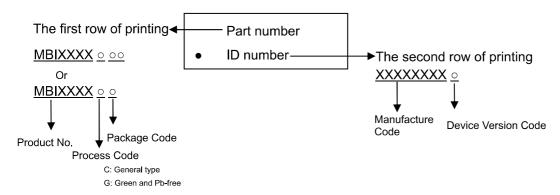
MBI5026CF\GF Outline Drawing



MBI5026CP\CPA\GP\GPA Outline Drawing

Note: The unit for the outline drawing is mm.

Product Top-mark Information



Product Revision History

Datasheet version	Device version code
VA.00	Not defined
VA.01	Α
VA.02	Α

Product Ordering Information

<u> </u>							
Part Number	Package Type	Weight (g)					
MBI5026CN	P-DIP24-300-2.54	1.628					
MBI5026CNS	SP-DIP24-300-1.78	1.11					
MBI5026CD	SOP24-300-1.27	0.617					
MBI5026CF	SOP24-300-1.00	0.28					
MBI5026CP	SSOP24-150-0.64	0.11					
MBI5026CPA	SSOP24-150-0.64	0.11					

Part Number	"Pb-free & Green"	Weight (g)
	Package Type	
MBI5026GN	P-DIP24-300-2.54	1.628
MBI5026GNS	SP-DIP24-300-1.78	1.11
MBI5026GD	SOP24-300-1.27	0.617
MBI5026GF	SOP24-300-1.00	0.28
MBI5026GP	SSOP24-150-0.64	0.11
MBI5026GPA	SSOP24-150-0.64	0.11